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**FOR DISCUSSION PURPOSES ONLY
PROPOSED CLAIM AMENDMENTS****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**IN RE APPLICATION OF: Whonchee Lee *et al.*

APPLICATION NO.: 09/888,002

FILED: June 21, 2001

**FOR: METHODS AND APPARATUS FOR
ELECTRICALLY AND/OR CHEMICALLY-
MECHANICALLY REMOVING
CONDUCTIVE MATERIAL FROM A
MICROELECTRONIC SUBSTRATE**

EXAMINER: Dung V. Nguyen

ART UNIT: 3723

CONF. NO: 9049

PROPOSED CLAIM AMENDMENTS**FOR DISCUSSION PURPOSES ONLY**Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In the Claims:

25. A method for removing electrically conductive material from a face surface of a microelectronic substrate, comprising:

engaging the microelectronic substrate with a polishing surface of a polishing pad;

coupling the conductive material to a source of electrical potential;

removing at least a portion of the conductive material from the microelectronic substrate by passing a varying current through the conductive material while moving at least one of the microelectronic substrate and the polishing pad relative to the other and while the microelectronic substrate is engaged with the polishing pad; and

removing gas from a region between the face surface of the microelectronic substrate and an electrode facing toward the face surface of the